

SN54ABT2952A, SN74ABT2952A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCBS203D – AUGUST 1992 – REVISED JANUARY 1998

- State-of-the-Art *EPIC-II^B*™ BiCMOS Design Significantly Reduces Power Dissipation
- Two 8-Bit Back-to-Back Registers Store Data Flowing in Both Directions
- Noninverting Outputs
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs

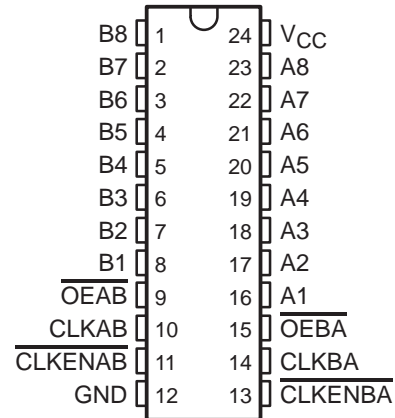
description

The 'ABT2952A transceivers consist of two 8-bit back-to-back registers that store data flowing in both directions between two bidirectional buses. Data on the A or B bus is stored in the registers on the low-to-high transition of the clock (CLKAB or CLKBA) input provided that the clock-enable (CLKENAB or CLKENBA) input is low. Taking the output-enable ($\overline{\text{OEAB}}$ or $\overline{\text{OEBA}}$) input low accesses the data on either port.

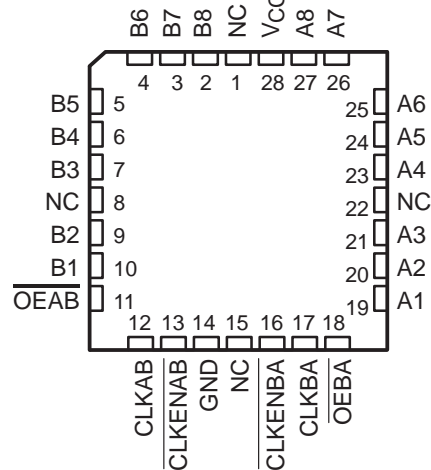
To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT2952A is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ABT2952A is characterized for operation from -40°C to 85°C .

SN54ABT2952A . . . JT OR W PACKAGE
SN74ABT2952A . . . DB, DW, PW, OR NT PACKAGE
(TOP VIEW)



SN54ABT2952A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

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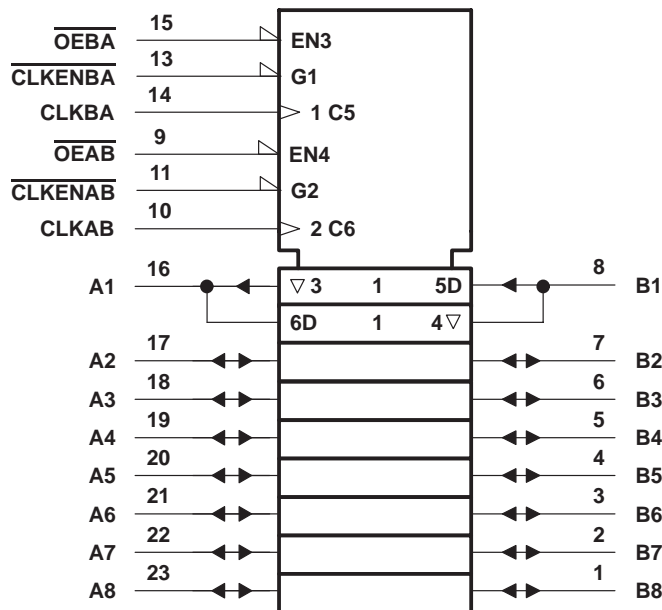
FUNCTION TABLE†

| INPUTS | | | | OUTPUT |
|---------|--------|------|---|------------------|
| CLKENAB | CLKAB | OEAB | A | B |
| H | X | L | X | B ₀ ‡ |
| X | H or L | L | X | B ₀ ‡ |
| L | ↑ | L | L | L |
| L | ↑ | L | H | H |
| X | X | H | X | Z |

† A-to-B data flow is shown; B-to-A data flow is similar, but uses $\overline{\text{CLKENBA}}$, CLKBA, and $\overline{\text{OEBA}}$.

‡ Level of B before the indicated steady-state input conditions were established

logic symbols§

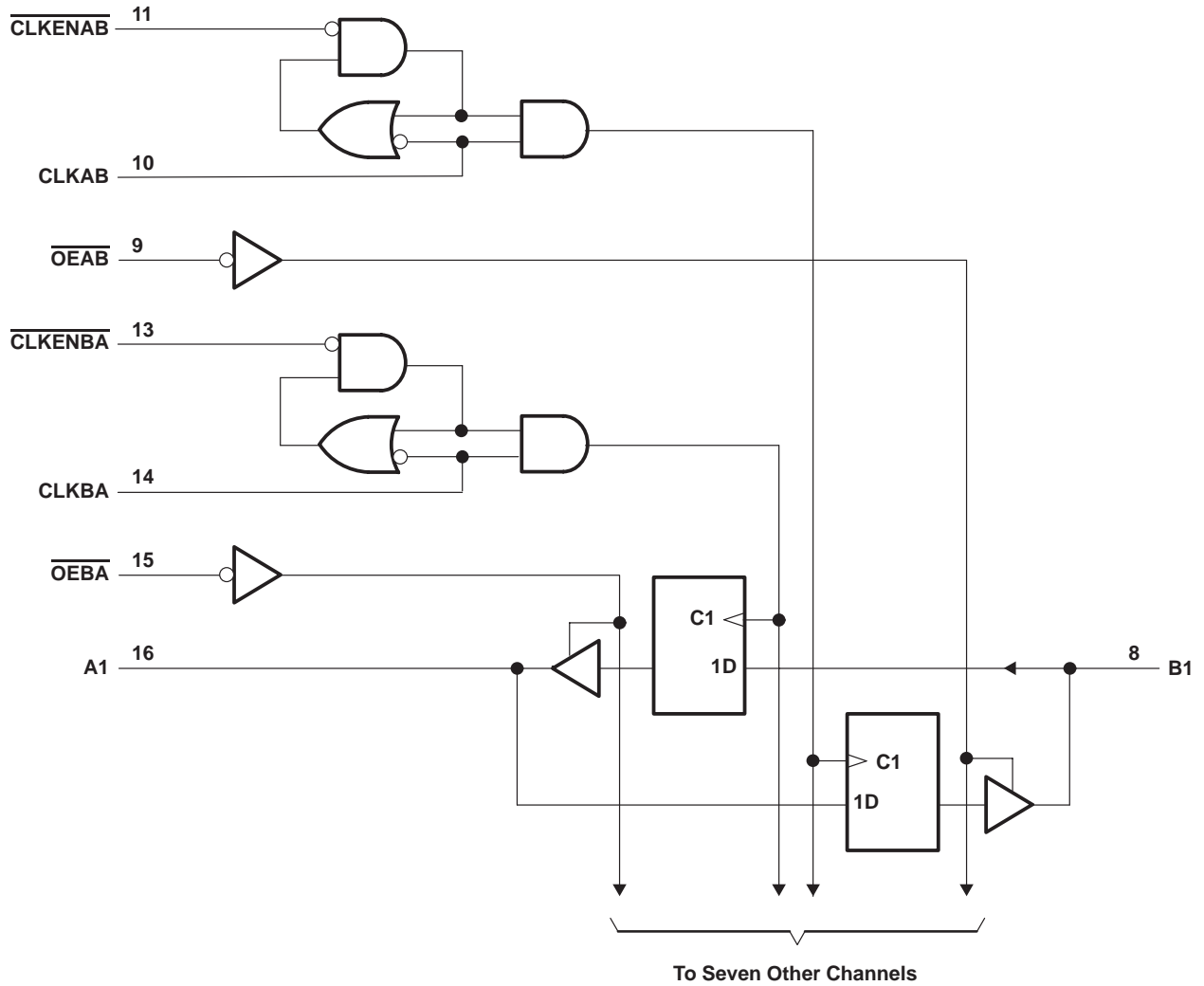


§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

SN54ABT2952A, SN74ABT2952A
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logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

SN54ABT2952A, SN74ABT2952A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | |
|---|-----------------|
| Supply voltage range, V_{CC} | -0.5 V to 7 V |
| Input voltage range, V_I (except I/O ports) (see Note 1) | -0.5 V to 7 V |
| Voltage range applied to any output in the high or power-off state, V_O | -0.5 V to 5.5 V |
| Current into any output in the low state, I_O : SN54ABT2952A | 96 mA |
| SN74ABT2952A | 128 mA |
| Input clamp current, I_{IK} ($V_I < 0$) | -18 mA |
| Output clamp current, I_{OK} ($V_O < 0$) | -50 mA |
| Package thermal impedance, θ_{JA} (see Note 2): DB package | 104°C/W |
| DW package | 81°C/W |
| NT package | 67°C/W |
| PW package | 120°C/W |
| Storage temperature range, T_{stg} | -65°C to 150°C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

| | | SN54ABT2952A | | SN74ABT2952A | | UNIT |
|---------------------|------------------------------------|-----------------|----------|--------------|----------|------|
| | | MIN | MAX | MIN | MAX | |
| V_{CC} | Supply voltage | 4.5 | 5.5 | 4.5 | 5.5 | V |
| V_{IH} | High-level input voltage | 2 | | 2 | | V |
| V_{IL} | Low-level input voltage | | 0.8 | | 0.8 | V |
| V_I | Input voltage | 0 | V_{CC} | 0 | V_{CC} | V |
| I_{OH} | High-level output current | | -24 | | -32 | mA |
| I_{OL} | Low-level output current | | 48 | | 64 | mA |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | Outputs enabled | | 10 | 10 | ns/V |
| T_A | Operating free-air temperature | -55 | 125 | -40 | 85 | °C |

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SN54ABT2952A, SN74ABT2952A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | T _A = 25°C | | | SN54ABT2952A | | SN74ABT2952A | | UNIT | |
|--------------------------|---|--|------------------|-------|--------------|------|--------------|------|------|----|
| | | MIN | TYP† | MAX | MIN | MAX | MIN | MAX | | |
| V _{IK} | V _{CC} = 4.5 V, I _I = -18 mA | | | -1.2 | | -1.2 | | -1.2 | V | |
| V _{OH} | V _{CC} = 4.5 V, I _{OH} = -3 mA | 2.5 | | | 2.5 | | | 2.5 | V | |
| | V _{CC} = 5 V, I _{OH} = -3 mA | 3 | | | 3 | | | 3 | | |
| | V _{CC} = 4.5 V | I _{OH} = -24 mA | 2 | | | 2 | | | | |
| I _{OH} = -32 mA | | 2* | | | | | | 2 | | |
| V _{OL} | V _{CC} = 4.5 V | I _{OL} = 48 mA | | 0.55 | | 0.55 | | | V | |
| | | I _{OL} = 64 mA | | 0.55* | | | | 0.55 | | |
| V _{hys} | | | 100 | | | | | | mV | |
| I _I | Control inputs | V _{CC} = 5.5 V, V _I = V _{CC} or GND | | ±1 | | ±1 | | ±1 | μA | |
| | A or B ports | | | ±100 | | ±100 | | ±100 | | |
| I _{OZH} ‡ | V _{CC} = 5.5 V, V _O = 2.7 V | | | 50* | | 10 | | 50 | μA | |
| I _{OZL} ‡ | V _{CC} = 5.5 V, V _O = 0.5 V | | | -50* | | -10 | | -50 | μA | |
| I _{off} | V _{CC} = 0, V _I or V _O ≤ 4.5 V | | | ±100* | | | | ±100 | μA | |
| I _{CEX} | V _{CC} = 5.5 V, V _O = 5.5 V | Outputs high | | 50 | | 50 | | 50 | μA | |
| I _O § | V _{CC} = 5.5 V, V _O = 2.5 V | | -50 | -100 | -180 | -50 | -180 | -50 | -180 | mA |
| I _{CC} | A or B ports | V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND | Outputs high | | 1 | 250 | 250 | 250 | 250 | μA |
| | | | Outputs low | | 24 | 35 | 35 | 35 | 35 | mA |
| | | | Outputs disabled | | 0.5 | 250 | 250 | 250 | 250 | μA |
| ΔI _{CC} ¶ | V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND | | | 1.5 | | 1.5 | | 1.5 | mA | |
| C _i | Control inputs | V _I = 2.5 V or 0.5 V | | 3.5 | | | | | pF | |
| C _{io} | A or B ports | V _O = 2.5 V or 0.5 V | | 7.5 | | | | | pF | |

* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at V_{CC} = 5 V.

‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

| | | V _{CC} = 5 V, T _A = 25°C | | SN54ABT2952A | | SN74ABT2952A | | UNIT | |
|--------------------|---------------------------------|--|-------------|--------------|-----|--------------|-----|------|----|
| | | MIN | MAX | MIN | MAX | MIN | MAX | | |
| f _{clock} | Clock frequency | 0 | 150 | 0 | 150 | 0 | 150 | MHz | |
| t _w | Pulse duration, CLK high or low | 3.3 | | 3.3 | | 3.3 | | ns | |
| t _{su} | Setup time before CLK↑ | A or B | High or low | 2.5 | | 3 | | 2.5 | ns |
| | | CLKEN | | 3 | | 3 | | | |
| t _h | Hold time after CLK↑ | A or B | | 1.5 | | 1.5 | | 1.5 | ns |
| | | CLKEN | | 2 | | 2 | | 2 | |



SN54ABT2952A, SN74ABT2952A
OCTAL BUS TRANSCEIVERS AND REGISTERS
WITH 3-STATE OUTPUTS

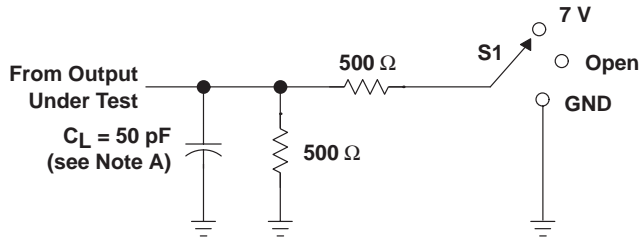
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CC} = 5$ V, $T_A = 25^\circ$ C | | | SN54ABT2952A | | SN74ABT2952A | | UNIT |
|-----------|--|-------------|---------------------------------------|-----|-----|--------------|-----|--------------|-----|------|
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| f_{max} | | | 150 | | | 150 | | 150 | | MHz |
| t_{PLH} | CLKAB or CLKBA | B or A | 2 | 3.3 | 5.2 | 2 | 6.3 | 2 | 5.9 | ns |
| t_{PHL} | | | 2.5 | 4 | 6.1 | 2.5 | 6.8 | 2.5 | 6.3 | |
| t_{PZH} | \overline{OEBA} or \overline{OEAB} | A or B | 1.5 | 3.2 | 4.7 | 1.5 | 5.7 | 1.5 | 5.6 | ns |
| t_{PZL} | | | 2 | 3.7 | 5.7 | 2 | 6.7 | 2 | 6.6 | |
| t_{PHZ} | \overline{OEBA} or \overline{OEAB} | A or B | 1.5 | 3.5 | 5.1 | 1.5 | 6.5 | 1.5 | 6.4 | ns |
| t_{PLZ} | | | 1.5 | 3.4 | 5.9 | 1.5 | 6.7 | 1.5 | 6.2 | |

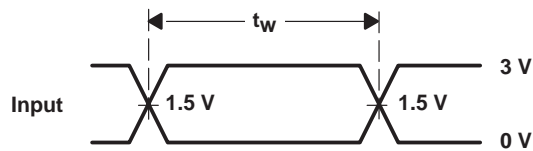


PARAMETER MEASUREMENT INFORMATION

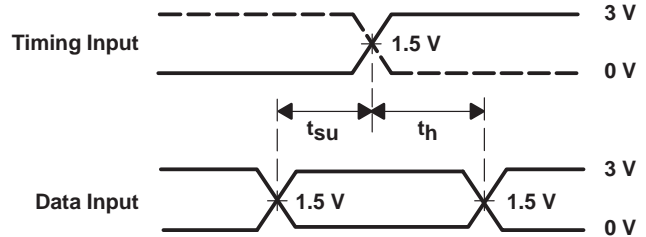


| TEST | S1 |
|-------------------|------|
| t_{PLH}/t_{PHL} | Open |
| t_{PLZ}/t_{PZL} | 7 V |
| t_{PHZ}/t_{PZH} | Open |

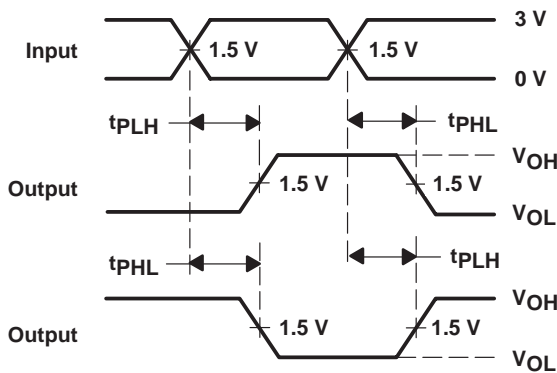
LOAD CIRCUIT



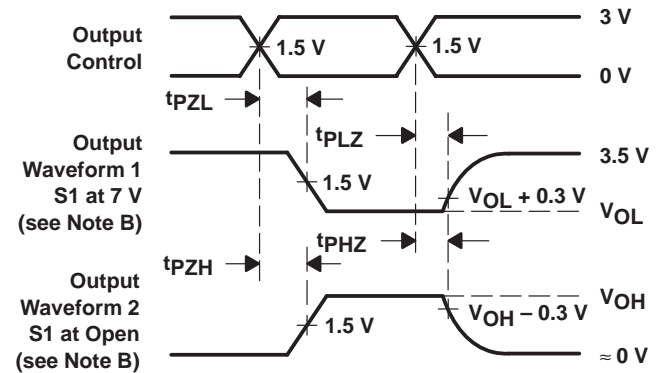
VOLTAGE WAVEFORMS
 PULSE DURATION



VOLTAGE WAVEFORMS
 SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
 PROPAGATION DELAY TIMES
 INVERTING AND NONINVERTING OUTPUTS







VOLTAGE WAVEFORMS
 ENABLE AND DISABLE TIMES
 LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|--|---|
| 5962-9308602QLA | ACTIVE | CDIP | JT | 24 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9308602QL A SNJ54ABT2952AJ T |  |
| SN74ABT2952ADBLE | OBSOLETE | SSOP | DB | 24 | | TBD | Call TI | Call TI | -40 to 85 | | |
| SN74ABT2952ADW | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | ABT2952A |  |
| SN74ABT2952ADWR | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | ABT2952A |  |
| SNJ54ABT2952AJT | ACTIVE | CDIP | JT | 24 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9308602QL A SNJ54ABT2952AJ T |  |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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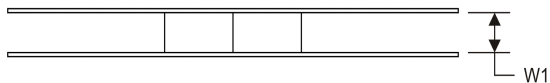
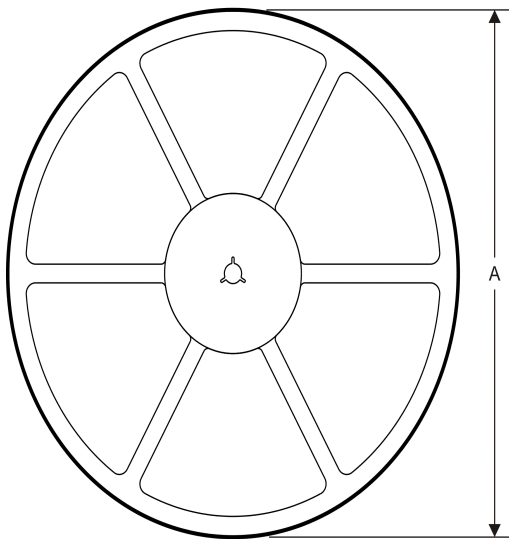
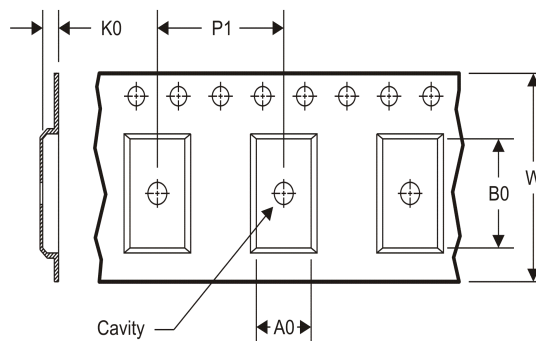
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OTHER QUALIFIED VERSIONS OF SN54ABT2952A, SN74ABT2952A :

- Catalog: [SN74ABT2952A](#)
- Military: [SN54ABT2952A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

TAPE AND REEL INFORMATION

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74ABT2952ADWR | SOIC | DW | 24 | 2000 | 330.0 | 24.4 | 10.75 | 15.7 | 2.7 | 12.0 | 24.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74ABT2952ADWR | SOIC | DW | 24 | 2000 | 367.0 | 367.0 | 45.0 |

JT (R-GDIP-T**)

CERAMIC DUAL-IN-LINE

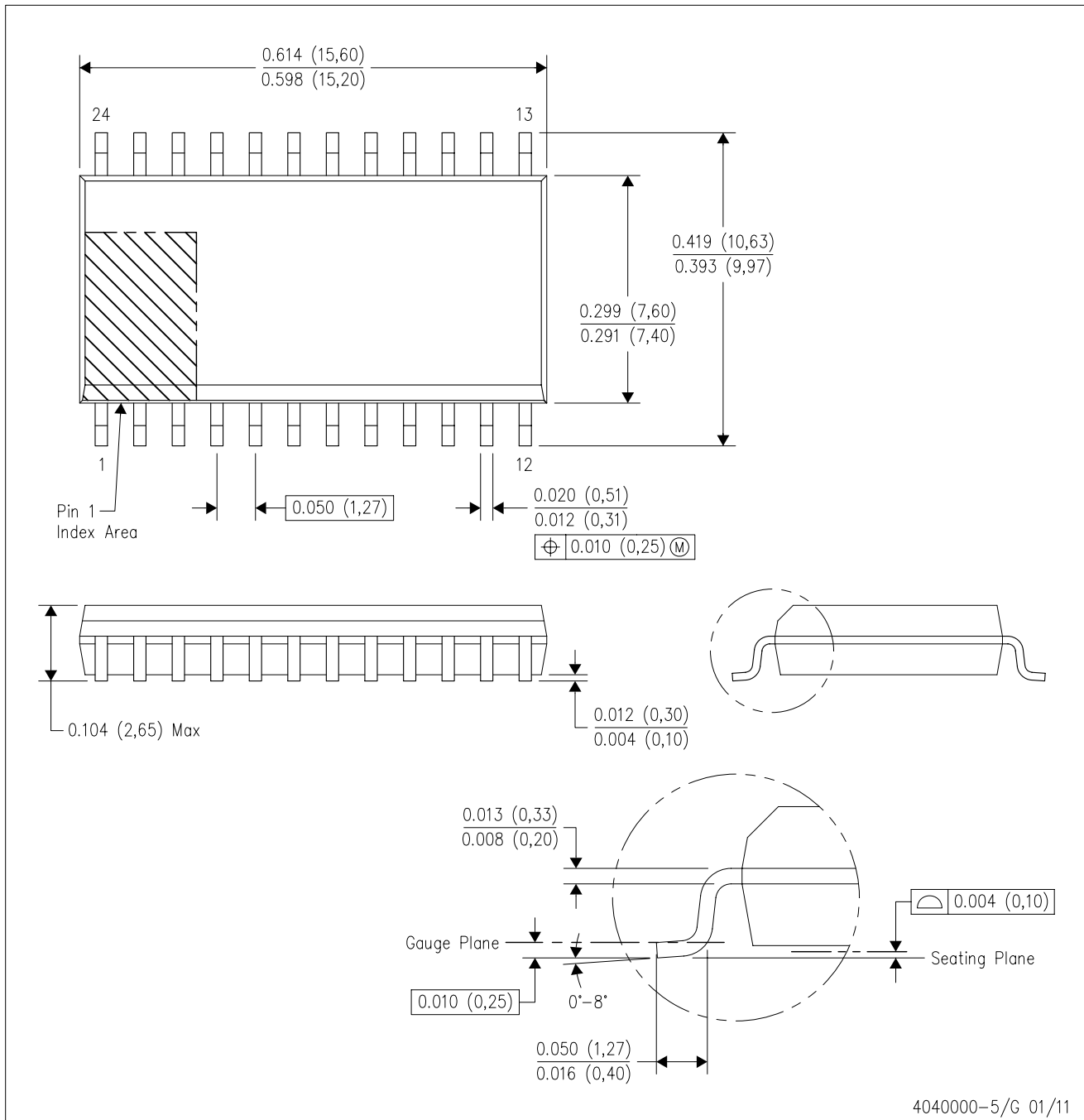
24 LEADS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification.
 E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

DW (R-PDSO-G24)

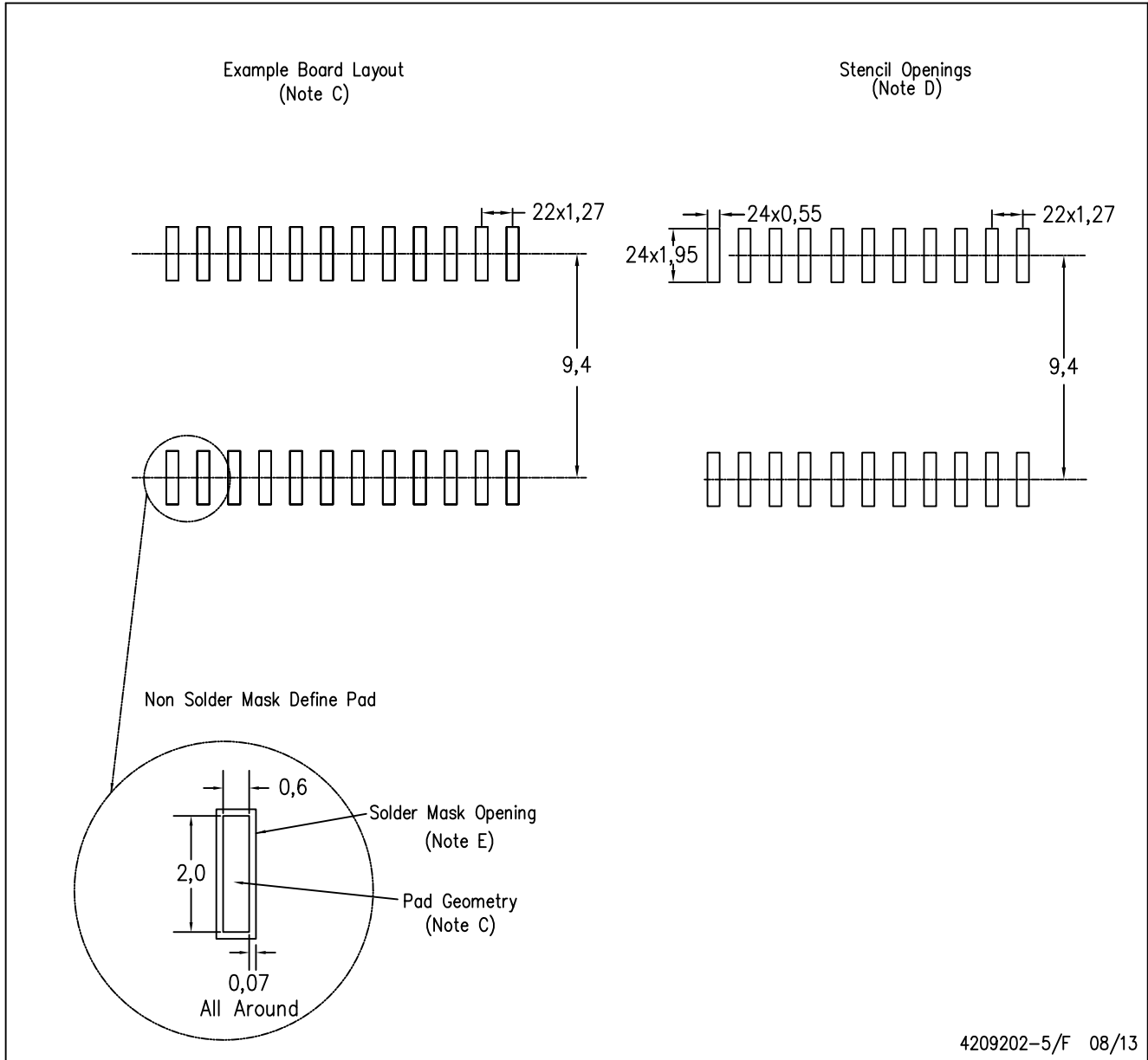
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AD.

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

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